Abstract of Disclosure

EDGE TRIMMING METHOD FOR SEMICONDUCTOR WAFER AND SEMICONDUCTOR WAFER HAVING TRIMMED EDGE

An edge trimming method includes providing a semiconductor wafer having a front side and a backside, trimming an edge of a periphery of the semiconductor wafer from the front side to form at least a notch region around the periphery of the front side of the semiconductor wafer, and providing the front side of the semiconductor wafer to a handle wafer. The notch region comprises a first wall and a second wall, and the first and the second wall are perpendicular to each other.

Figure 4